

In the claims

1. (Currently Amended) A crystalline substrate based device comprising:
a crystalline substrate having formed thereon a microstructure; and
at least one transparent chip scale packaging layer which is sealed over said microstructure by means of an adhesive and defines therewith at least one gap between said crystalline substrate and said at least one transparent chip scale packaging layer, said crystalline substrate, said microstructure and said transparent chip scale packaging layer forming a chip scale package,
wherein said microstructure receives light via said at least one transparent chip scale packaging layer.
2. (Original) A crystalline substrate based device according to claim 1 and wherein said at least one packaging layer is sealed onto said crystalline substrate using an adhesive.
3. (Original) A crystalline substrate based device according to claim 2 and wherein said adhesive comprises epoxy.
4. (Original) A crystalline substrate based device according to claim 1 and wherein said crystalline substrate comprises silicon.
5. (Cancelled)

6. (Previously Presented) A crystalline substrate based device according to claim 1 and wherein said at least one gap comprises a plurality of gaps.

7. (Original) A crystalline substrate based device according to claim 1 and wherein said microstructure comprises a micromechanical structure.

8. (Original) A crystalline substrate based device according to claim 1 and wherein said microstructure comprises a microelectronic structure.

9. (Original) A crystalline substrate based device according to claim 1 and wherein said microstructure comprises a optoelectronic structure.

10. (Previously Presented) A chip scale packaged crystalline substrate comprising:
a substrate having formed thereon a microstructure; and
at least one chip scale package which is sealed over said microstructure and defines therewith at least one gap,
and wherein said at least one package is at least partially transparent.

11. (Original) A chip scale packaged crystalline substrate according to claim 10 and wherein said at least one package is sealed onto said substrate using an adhesive.

12. (Original) A chip scale packaged crystalline substrate based device according to claim 11 and wherein said adhesive comprises epoxy.

13. (Original) A chip scale packaged crystalline substrate according to claim 10 and wherein said substrate comprises silicon.

14. (Original) A chip scale packaged crystalline substrate according to claim 10 and wherein said substrate comprises lithium niobate.

15. (Cancelled)

16. (Previously Presented) A chip scale packaged crystalline substrate according to claim 10 and wherein said at least one gap comprises a plurality of gaps.

17. (Original) A chip scale packaged crystalline substrate according to claim 10 and wherein said microstructure comprises a micromechanical structure.

18. (Original) A chip scale packaged crystalline substrate according to claim 10 and wherein said microstructure comprises a microelectronic structure.

19. (Currently Amended) A chip scale packaged crystalline substrate according to claim [[1]] 10 and wherein said microstructure comprises an optoelectronic structure.

20-29. (Cancelled)

30. (Original) A crystalline substrate based device according to claim 1 and wherein said crystalline substrate comprises lithium tantalate.

31. (Original) A crystalline substrate based device according to claim 1 and wherein said microstructure comprises a surface acoustic wave device.

32. (Currently Amended) A ~~device~~ chip scale packaged crystalline substrate according to claim ~~[[1]]~~ 10 and wherein said microstructure comprises a surface acoustic wave device.

33-34. (Cancelled)

35. (Original) A crystalline substrate based device according to claim 1 and wherein said crystalline substrate comprises quartz.

36. (Cancelled)

37. (Currently Amended) A chip scale packaged crystalline substrate based device comprising:

a crystalline substrate having formed thereon a microstructure; and

at least one chip scale package comprising at least one transparent packaging layer which is sealed over said microstructure by means of an adhesive and defines therewith at least one gap between said crystalline substrate and said at least one transparent packaging layer,

wherein said microstructure receives light via said at least one transparent packaging layer.

38. (Currently Amended) A crystalline substrate based device comprising:

a crystalline substrate having formed thereon a microstructure; and

at least one chip scale packaging layer which is sealed over said microstructure and defines therewith at least one gap between said crystalline substrate and said at least one chip scale packaging layer, the crystalline substrate, microstructure and chip scale packaging layer forming a chip scale package,

the chip scale package having a multiplicity of electrical contacts plated along edge surfaces thereof.

39. (Previously Presented) A device according to claim 38 wherein at least one gap is located over said crystalline substrate and under said at least one packaging layer.

40. (Previously Presented) A device according to claim 38 wherein said packaging layer is sealed over said microstructure by means of an adhesive.

41-54. (Cancelled)

55. (Previously Presented) A device according to claim 1, the substrate, microstructure and packaging layer forming a chip scale package having a multiplicity of electrical contacts plated along edge surfaces thereof.

56-59. (Cancelled)

60. (Previously Presented) A crystalline substrate based device comprising:

a microstructure on a substrate; and

a spacer on said substrate, said spacer defining at least one cavity extending entirely therethrough; and

at least one transparent packaging layer adhesively sealed onto said spacer over said microstructure and at least partially spaced therefrom, thereby to define a gap at said at least one cavity between said microstructure and said at least one packaging layer, wherein the substrate, microstructure and packaging layer form a chip scale package having a multiplicity of electrical contacts plated along edge surfaces thereof.

61. (Previously Presented) A crystalline substrate based device according to claim 60 and wherein said at least one packaging layer is sealed onto said crystalline substrate using an adhesive.

62. (Previously Presented) A crystalline substrate based device according to claim 61 and wherein said adhesive comprises Epoxy.

63. (Previously Presented) A crystalline substrate based device according to claim 60 and wherein said crystalline substrate comprises silicon.

64. (Previously Presented) A crystalline substrate based device according to claim 60 and wherein said crystalline substrate comprises lithium niobate.

65. (Previously Presented) A crystalline substrate based device comprising:
a microstructure on a substrate; and
at least one packaging layer;
a spacer on said packaging layer, said spacer defining at least one cavity extending entirely therethrough; and
said at least one packaging layer adhesively sealed onto said spacer over said microstructure and at least partially spaced therefrom, thereby to define a gap at said at least one cavity between said microstructure and said at least one packaging layer, wherein the substrate, microstructure and packaging layer form a chip scale package having a multiplicity of electrical contacts plated along edge surfaces thereof.

66. (Previously Presented) A crystalline substrate based device according to claim 60 and wherein said at least one gap comprises a plurality of gaps.

67. (Previously Presented) A crystalline substrate based device according to claim 60 and wherein said microstructure comprises a micromechanical structure.

68. (Previously Presented) A crystalline substrate based device according to claim 60 and wherein said microstructure comprises a microelectronic structure.

69. (Previously Presented) A crystalline substrate based device according to claim 60 and wherein said microstructure comprises a optoelectronic structure.

70-72. (Cancelled)

73. (Previously Presented) A crystalline substrate based device according to claim 60 and wherein said crystalline substrate comprises lithium tantalate.

74. (Previously Presented) A crystalline substrate based device according to claim 60 and wherein said microstructure comprises a surface acoustic wave device.

75. (Cancelled)

76. (Previously Presented) A crystalline substrate based device according to claim 60 and wherein said crystalline substrate comprises quartz.

77-80. (Cancelled)

81. (Previously Presented) A device according to claim 65 wherein said packaging layer comprises a transparent packaging layer.